

TSOP, FP-BGA
Commercial Temp
Industrial Temp

64K x 16

1Mb Asynchronous SRAM

7, 8, 10, 12 ns
3.3 V V_{DD}
Center V_{DD} and V_{SS}

Features

- Fast access time: 7, 8, 10, 12 ns
- CMOS low power operation: 145/125/100/85 mA at minimum cycle time
- Single 3.3 V power supply
- All inputs and outputs are TTL-compatible
- Byte control
- Fully static operation
- Industrial Temperature Option: -40° to 85°C
- Package line up
 - GP: RoHS-compliant 400 mil, 44-pin TSOP Type II package
 - U: 6 mm x 8 mm Fine Pitch Ball Grid Array package
 - GU: RoHS-compliant 6 mm x 8 mm Fine Pitch Ball Grid Array package

Description

The GS71116A is a high speed CMOS static RAM organized as 65,536-words by 16-bits. Static design eliminates the need for external clocks or timing strobes. Operating on a single 3.3 V power supply and all inputs and outputs are TTL-compatible. The GS71116A is available in the 6 mm x 8 mm Fine Pitch BGA and 400 mil TSOP Type-II packages.

Pin Descriptions

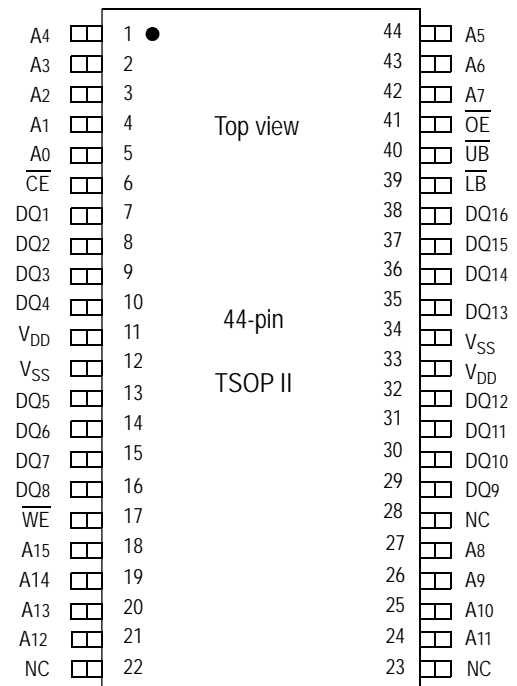
Symbol	Description
A ₀ –A ₁₅	Address input
DQ ₁ –DQ ₁₆	Data input/output
$\overline{\text{CE}}$	Chip enable input
$\overline{\text{LB}}$	Lower byte enable input (DQ1 to DQ8)
$\overline{\text{UB}}$	Upper byte enable input (DQ9 to DQ16)
$\overline{\text{WE}}$	Write enable input
$\overline{\text{OE}}$	Output enable input
V_{DD}	+3.3 V power supply
V_{SS}	Ground
NC	No connect

Fine Pitch BGA 64K x 16-Bump Configuration

	1	2	3	4	5	6
A	$\overline{\text{LB}}$	$\overline{\text{OE}}$	A ₀	A ₁	A ₂	NC
B	DQ ₁₆	$\overline{\text{UB}}$	A ₃	A ₄	$\overline{\text{CE}}$	DQ ₁
C	DQ ₁₄	DQ ₁₅	A ₅	A ₆	DQ ₂	DQ ₃
D	V_{SS}	DQ ₁₃	NC	A ₇	DQ ₄	V_{DD}
E	V_{DD}	DQ ₁₂	NC	NC	DQ ₅	V_{SS}
F	DQ ₁₁	DQ ₁₀	A ₈	A ₉	DQ ₇	DQ ₆
G	DQ ₉	NC	A ₁₀	A ₁₁	$\overline{\text{WE}}$	DQ ₈
H	NC	A ₁₂	A ₁₃	A ₁₄	A ₁₅	NC

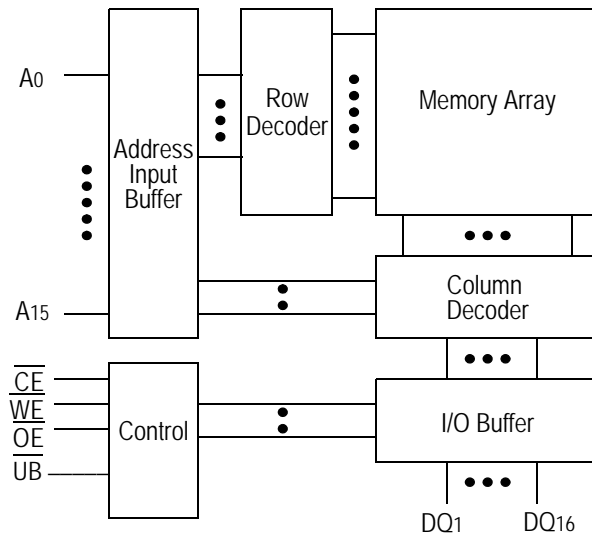
6 mm x 8 mm, 0.75 mm Bump Pitch (Package U)
Top View

TSOP-II 64K x 16-Pin Configuration



Package TP

Block Diagram



Truth Table

\overline{CE}	\overline{OE}	\overline{WE}	\overline{LB}	\overline{UB}	DQ1 to DQ8	DQ9 to DQ16	V_{DD} Current
H	X	X	X	X	Not Selected	Not Selected	ISB1, ISB2
L	L	H	L	L	Read	Read	I _{DD}
			L	H	Read	High Z	
			H	L	High Z	Read	
L	X	L	L	L	Write	Write	
			L	H	Write	Not Write, High Z	
			H	L	Not Write, High Z	Write	
L	H	H	X	X	High Z	High Z	
L	X	X	H	H	High Z	High Z	

Note:

X: "H" or "L"

Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
Supply Voltage	V_{DD}	-0.5 to +4.6	V
Input Voltage	V_{IN}	-0.5 to $V_{DD} + 0.5$ (≤ 4.6 V max.)	V
Output Voltage	V_{OUT}	-0.5 to $V_{DD} + 0.5$ (≤ 4.6 V max.)	V
Allowable power dissipation	PD	0.7	W
Storage temperature	T_{STG}	-55 to 150	$^{\circ}C$

Note:

Permanent device damage may occur if Absolute Maximum Ratings are exceeded. Functional operation shall be restricted to Recommended Operating Conditions. Exposure to higher than recommended voltages for extended periods of time could affect device reliability.

Recommended Operating Conditions

Parameter	Symbol	Min	Typ	Max	Unit
Supply Voltage for -7/-8/-10/-12	V_{DD}	3.0	3.3	3.6	V
Input High Voltage	V_{IH}	2.0	—	$V_{DD} + 0.3$	V
Input Low Voltage	V_{IL}	-0.3	—	0.8	V
Ambient Temperature, Commercial Range	T_{Ac}	0	—	70	$^{\circ}C$
Ambient Temperature, Industrial Range	T_{AI}	-40	—	85	$^{\circ}C$

Notes:

1. Input overshoot voltage should be less than $V_{DD} + 2$ V and not exceed 20 ns.
2. Input undershoot voltage should be greater than -2 V and not exceed 20 ns.

Capacitance

Parameter	Symbol	Test Condition	Max	Unit
Input Capacitance	C_{IN}	$V_{IN} = 0$ V	5	pF
Output Capacitance	C_{OUT}	$V_{OUT} = 0$ V	7	pF

Notes:

1. Tested at $T_A = 25^{\circ}C$, $f = 1$ MHz
2. These parameters are sampled and are not 100% tested.

DC I/O Pin Characteristics

Parameter	Symbol	Test Conditions	Min	Max
Input Leakage Current	I_{IL}	$V_{IN} = 0 \text{ to } V_{DD}$	-1 μ A	1 μ A
Output Leakage Current	I_{LO}	Output High Z $V_{OUT} = 0 \text{ to } V_{DD}$	-1 μ A	1 μ A
Output High Voltage	V_{OH}	$I_{OH} = -4 \text{ mA}$	2.4	
Output Low Voltage	V_{OL}	$I_{LO} = +4 \text{ mA}$		0.4V

Power Supply Currents

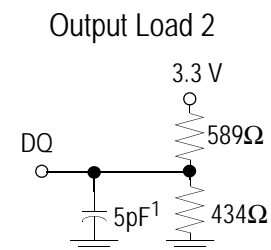
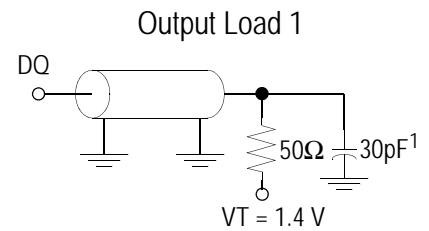
Parameter	Symbol	Test Conditions	0 to 70°C				-40 to 85°C			
			7 ns	8 ns	10 ns	12 ns	7 ns	8 ns	10 ns	12 ns
Operating Supply Current	I_{DD}	$\overline{CE} \leq V_{IL}$ All other inputs $\geq V_{IH}$ or $\leq V_{IL}$ Min. cycle time $I_{OUT} = 0 \text{ mA}$	145 mA	125 mA	100 mA	85 mA	150 mA	130 mA	105 mA	90 mA
Standby Current	I_{SB1}	$\overline{CE} \geq V_{IH}$ All other inputs $\geq V_{IH}$ or $\leq V_{IL}$ Min. cycle time	25 mA	20 mA	20 mA	15 mA	30 mA	25 mA	25 mA	20 mA
Standby Current	I_{SB2}	$\overline{CE} \geq V_{DD} - 0.2 \text{ V}$ All other inputs $\geq V_{DD} - 0.2 \text{ V}$ or $\leq 0.2 \text{ V}$	2 mA				5 mA			

AC Test Conditions

Parameter	Conditions
Input high level	$V_{IH} = 2.4 \text{ V}$
Input low level	$V_{IL} = 0.4 \text{ V}$
Input rise time	$t_r = 1 \text{ V/ns}$
Input fall time	$t_f = 1 \text{ V/ns}$
Input reference level	1.4 V
Output reference level	1.4 V
Output load	Fig. 1 & 2

Notes:

1. Include scope and jig capacitance.
2. Test conditions as specified with output loading as shown in Fig. 1 unless otherwise noted.
3. Output load 2 for t_{LZ} , t_{HZ} , t_{OLZ} and t_{OHZ}



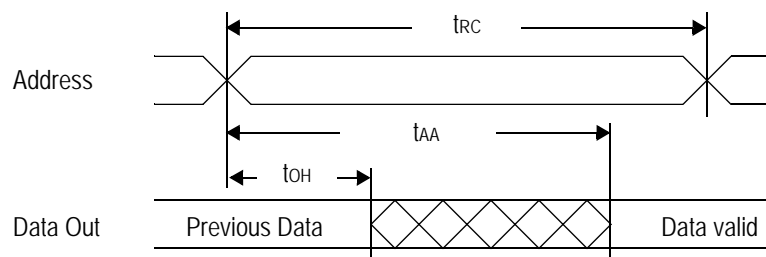
AC Characteristics

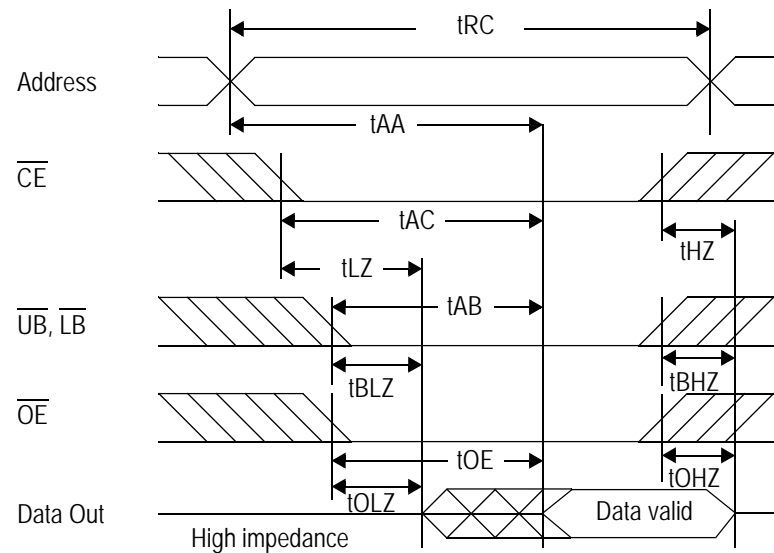
Read Cycle

Parameter	Symbol	-7		-8		-10		-12		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
Read cycle time	t_{RC}	7	—	8	—	10	—	12	—	ns
Address access time	t_{AA}	—	7	—	8	—	10	—	12	ns
Chip enable access time (\overline{CE})	t_{AC}	—	7	—	8	—	10	—	12	ns
Byte enable access time (\overline{UB} , \overline{LB})	t_{AB}	—	3	—	3.5	—	4	—	5	ns
Output enable to output valid (\overline{OE})	t_{OE}	—	3	—	3.5	—	4	—	5	ns
Output hold from address change	t_{OH}	3	—	3	—	3	—	3	—	ns
Chip enable to output in low Z (\overline{CE})	t_{LZ}^*	3	—	3	—	3	—	3	—	ns
Output enable to output in low Z (\overline{OE})	t_{OLZ}^*	0	—	0	—	0	—	0	—	ns
Byte enable to output in low Z (\overline{UB} , \overline{LB})	t_{BLZ}^*	0	—	0	—	0	—	0	—	ns
Chip disable to output in High Z (\overline{CE})	t_{HZ}^*	—	3.5	—	4	—	5	—	6	ns
Output disable to output in High Z (\overline{OE})	t_{OHZ}^*	—	3	—	3.5	—	4	—	5	ns
Byte disable to output in High Z (\overline{UB} , \overline{LB})	t_{BHZ}^*	—	3	—	3.5	—	3.5	—	3.5	—

* These parameters are sampled and are not 100% tested.

Read Cycle 1: $\overline{CE} = \overline{OE} = V_{IL}$, $\overline{WE} = V_{IH}$, \overline{UB} and, or $\overline{LB} = V_{IL}$

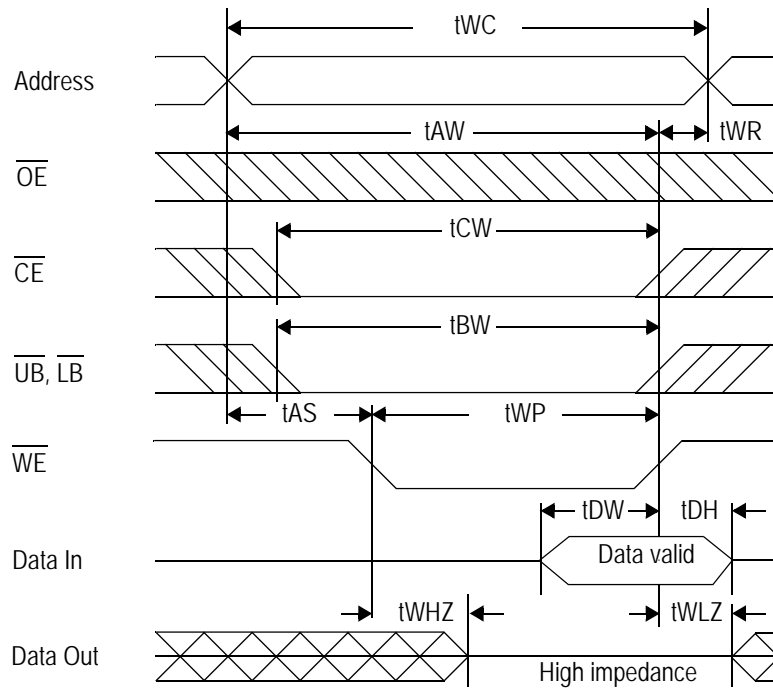
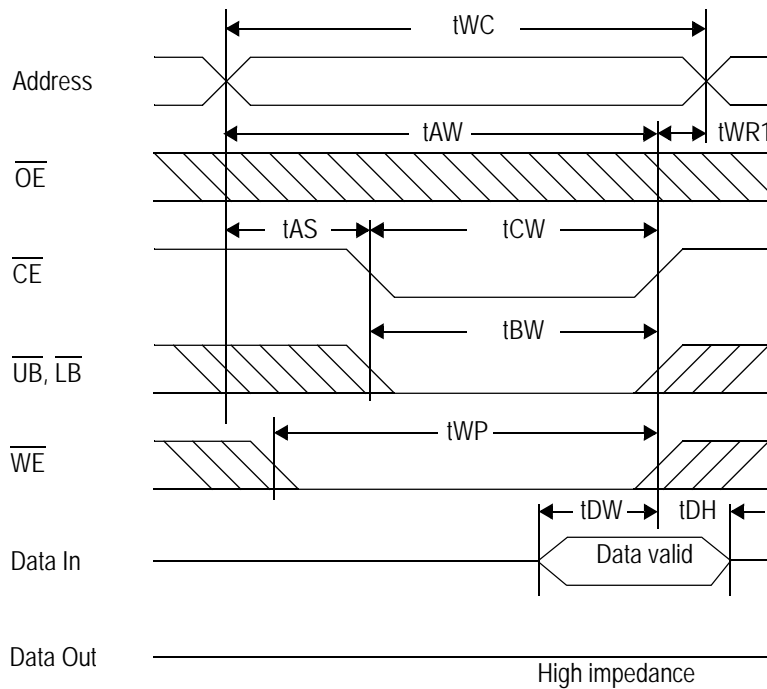


Read Cycle 2: $\overline{WE} = V_{IH}$


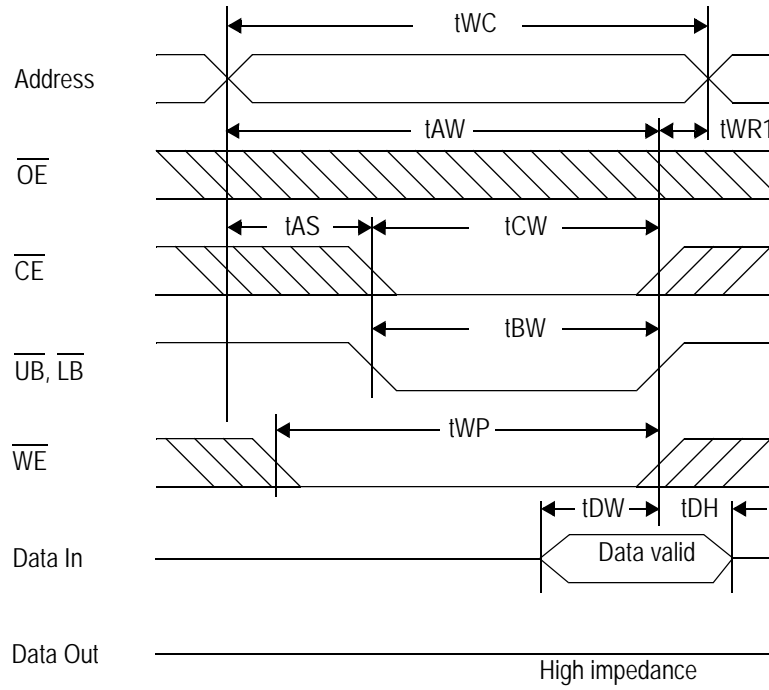
Write Cycle

Parameter	Symbol	-7		-8		-10		-12		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
Write cycle time	t_{WC}	7	—	8	—	10	—	12	—	ns
Address valid to end of write	t_{AW}	5	—	5.5	—	7	—	8	—	ns
Chip enable to end of write	t_{CW}	5	—	5.5	—	7	—	8	—	ns
Byte enable to end of write	t_{BW}	5	—	5.5	—	7	—	8	—	ns
Data set up time	t_{DW}	3.5	—	4	—	5	—	6	—	ns
Data hold time	t_{DH}	0	—	0	—	0	—	0	—	ns
Write pulse width	t_{WP}	5	—	5.5	—	7	—	8	—	ns
Address set up time	t_{AS}	0	—	0	—	0	—	0	—	ns
Write recovery time (\overline{WE})	t_{WR}	0	—	0	—	0	—	0	—	ns
Write recovery time (\overline{CE})	t_{WR1}	0	—	0	—	0	—	0	—	ns
Output Low Z from end of write	t_{WLZ}^*	3	—	3	—	3	—	3	—	ns
Write to output in High Z	t_{WHZ}^*	—	3	—	3.5	—	4	—	5	ns

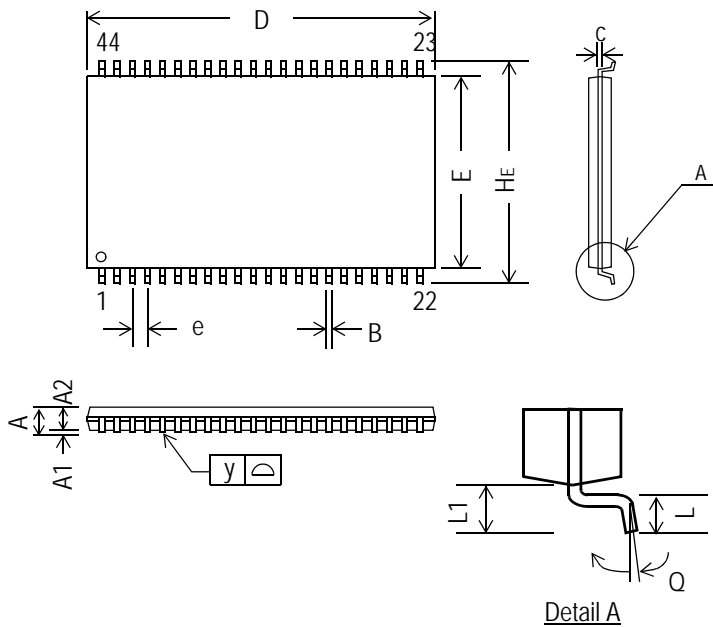
* These parameters are sampled and are not 100% tested.

Write Cycle 1: \overline{WE} control

 Write Cycle 2: \overline{CE} control


Write Cycle 3: \overline{UB} , \overline{LB} control



44 Pin, 400 mil TSOP-II

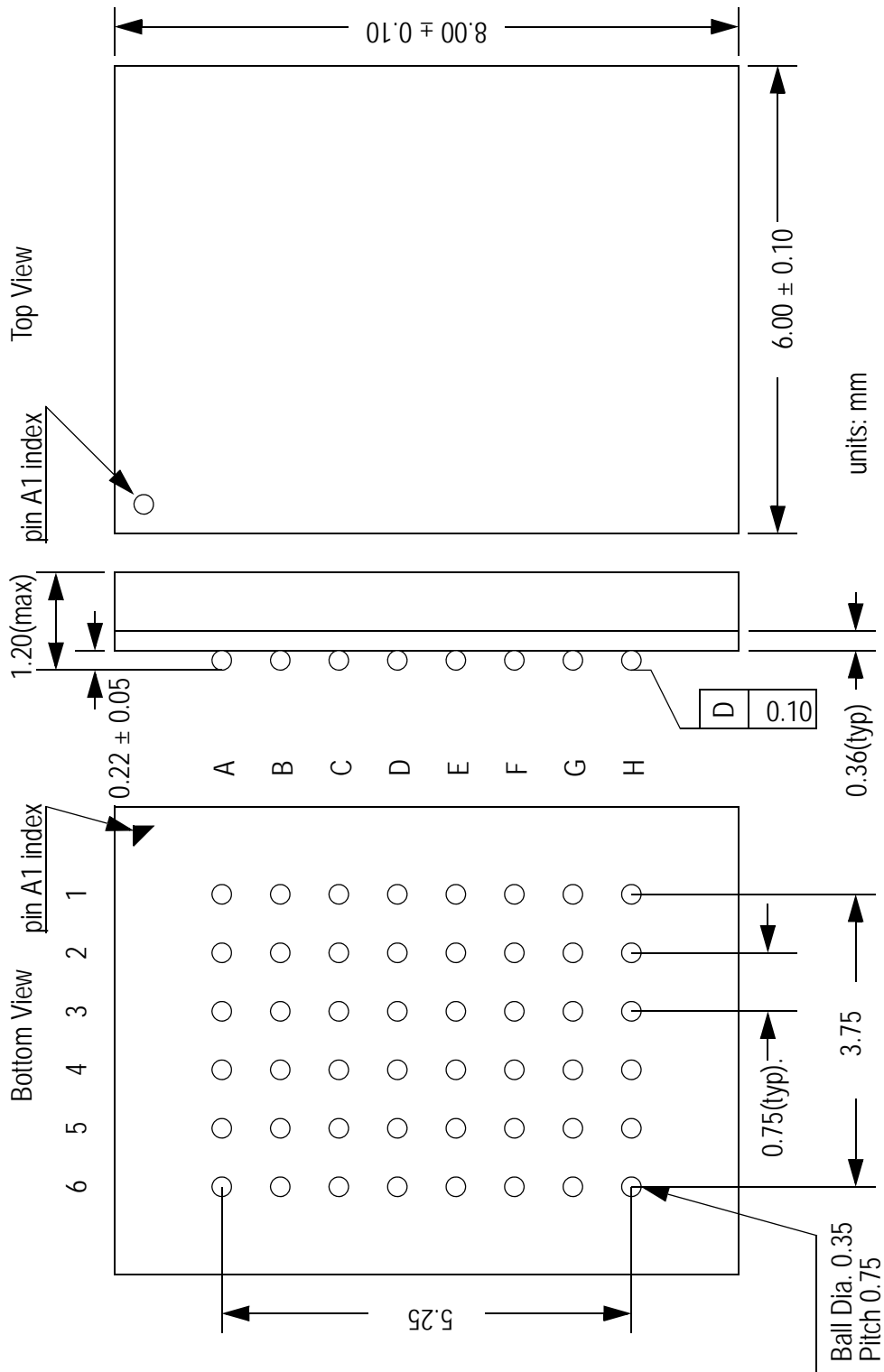


Symbol	Dimension in inch			Dimension in mm		
	min	nom	max	min	nom	max
A	—	—	0.047	—	—	1.20
A1	0.002	—	—	0.05	—	—
A2	0.037	0.039	0.041	0.95	1.00	1.05
B	0.01	0.014	0.018	0.25	0.35	0.45
c	—	0.006	—	—	0.15	—
D	0.721	0.725	0.729	18.31	18.41	18.51
E	0.396	0.400	0.404	10.06	10.16	10.26
e	—	0.031	—	—	0.80	—
HE	0.455	0.463	0.471	11.56	11.76	11.96
L	0.016	0.020	0.024	0.40	0.50	0.60
L1	—	0.031	—	—	0.80	—
y	—	—	0.004	—	—	0.10
Q	0°	—	5°	0°	—	5°

Notes:

1. Dimension D & E do not include interlead flash.
2. Dimension B does not include dambar protrusion/intrusion.
3. Controlling dimension: mm

6 mm x 8 mm Fine Pitch BGA



Ordering Information

Part Number*	Package	Access Time	Temp. Range
GS71116AGP-7	RoHS-compliant 400 mil TSOP-II	7 ns	Commercial
GS71116AGP-8	RoHS-compliant 400 mil TSOP-II	8 ns	Commercial
GS71116AGP-10	RoHS-compliant 400 mil TSOP-II	10 ns	Commercial
GS71116AGP-12	RoHS-compliant 400 mil TSOP-II	12 ns	Commercial
GS71116AGP-7I	RoHS-compliant 400 mil TSOP-II	7 ns	Industrial
GS71116AGP-8I	RoHS-compliant 400 mil TSOP-II	8 ns	Industrial
GS71116AGP-10I	RoHS-compliant 400 mil TSOP-II	10 ns	Industrial
GS71116AGP-12I	RoHS-compliant 400 mil TSOP-II	12 ns	Industrial
GS71116AU-7	6 mm x 8 mm Fine Pitch BGA	7 ns	Commercial
GS71116AU-8	6 mm x 8 mm Fine Pitch BGA	8 ns	Commercial
GS71116AU-10	6 mm x 8 mm Fine Pitch BGA	10 ns	Commercial
GS71116AU-12	6 mm x 8 mm Fine Pitch BGA	12 ns	Commercial
GS71116AU-7I	6 mm x 8 mm Fine Pitch BGA	7 ns	Industrial
GS71116AU-8I	6 mm x 8 mm Fine Pitch BGA	8 ns	Industrial
GS71116AU-10I	6 mm x 8 mm Fine Pitch BGA	10 ns	Industrial
GS71116AU-12I	6 mm x 8 mm Fine Pitch BGA	12 ns	Industrial
GS71116AGU-7	RoHS-compliant 6 mm x 8 mm Fine Pitch BGA	7 ns	Commercial
GS71116AGU-8	RoHS-compliant 6 mm x 8 mm Fine Pitch BGA	8 ns	Commercial
GS71116AGU-10	RoHS-compliant 6 mm x 8 mm Fine Pitch BGA	10 ns	Commercial
GS71116AGU-12	RoHS-compliant 6 mm x 8 mm Fine Pitch BGA	12 ns	Commercial
GS71116AGU-7I	RoHS-compliant 6 mm x 8 mm Fine Pitch BGA	7 ns	Industrial
GS71116AGU-8I	RoHS-compliant 6 mm x 8 mm Fine Pitch BGA	8 ns	Industrial
GS71116AGU-10I	RoHS-compliant 6 mm x 8 mm Fine Pitch BGA	10 ns	Industrial
GS71116AGU-12I	RoHS-compliant 6 mm x 8 mm Fine Pitch BGA	12 ns	Industrial

Note:

Customers requiring delivery in Tape and Reel should add the character "T" to the end of the part number. For example: GS71116AGP-8T.